



PQMB11

PNP/PNP resistor-equipped transistors;
R1 = 10 k Ω , R2 = 10 k Ω

26 October 2015

Product data sheet

1. General description

PNP/PNP Resistor-Equipped Transistors (RET) in a leadless ultra small DFN1010B-6 (SOT1216) Surface-Mounted Device (SMD) plastic package.

NPN/NPN complement: PQMH11.

NPN/PNP complement: PQMD3.

2. Features and benefits

- 100 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Low package height of 0.37 mm
- Reduces component count
- Reduces pick and place costs
- AEC-Q101 qualified

3. Applications

- Low current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications
- Mobile applications

4. Quick reference data

Table 1. Quick reference data

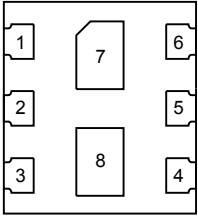
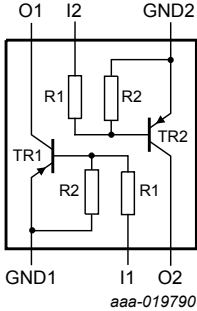
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Per transistor							
V _{CEO}	collector-emitter voltage	open base	-	-	-50	V	
I _O	output current		-	-	-100	mA	
Per transistor							
R1	bias resistor 1	T _{amb} = 25 °C	[1]	7	10	13	k Ω
R2/R1	bias resistor ratio		[1]	0.8	1	1.2	

[1] See section "Test information" for resistor calculation and test conditions.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	GND1	GND (emitter) TR1	 <p>Transparent top view DFN1010B-6 (SOT1216)</p>	 <p>aaa-019790</p>
2	I1	input (base) TR1		
3	O2	output (collector) TR2		
4	GND2	GND (emitter) TR2		
5	I2	input (base) TR2		
6	O1	output (collector) TR1		
7	O1	output (collector) TR1		
8	O2	output (collector) TR2		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PQMB11	DFN1010B-6	DFN1010B-6: plastic thermal enhanced ultra thin small outline package; no leads; 6 terminals	SOT1216

7. Marking

Table 4. Marking codes

Type number	Marking code
PQMB11	A 110

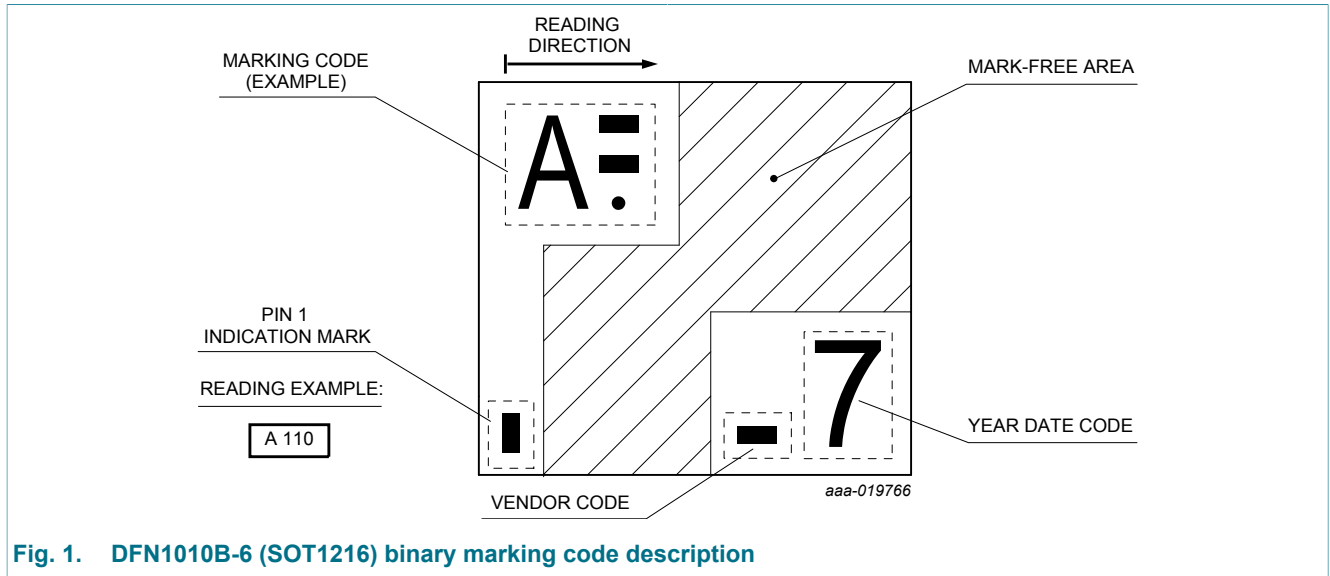


Fig. 1. DFN1010B-6 (SOT1216) binary marking code description

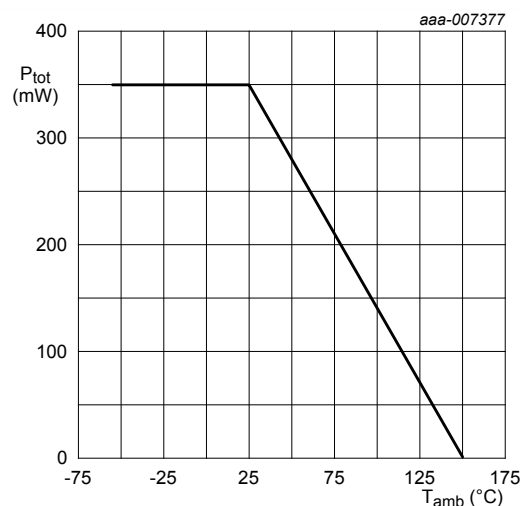
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per transistor						
V _{CB0}	collector-base voltage	open emitter		-	-50	V
V _{CEO}	collector-emitter voltage	open base		-	-50	V
V _{EBO}	emitter-base voltage	open collector		-	-10	V
V _I	input voltage	positive		-	10	V
		negative		-	-40	V
I _O	output current			-	-100	mA
I _{CM}	peak collector current			-	-100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	230	mW
Per device						
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	350	mW
T _j	junction temperature			-	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



FR4 PCB, standard footprint

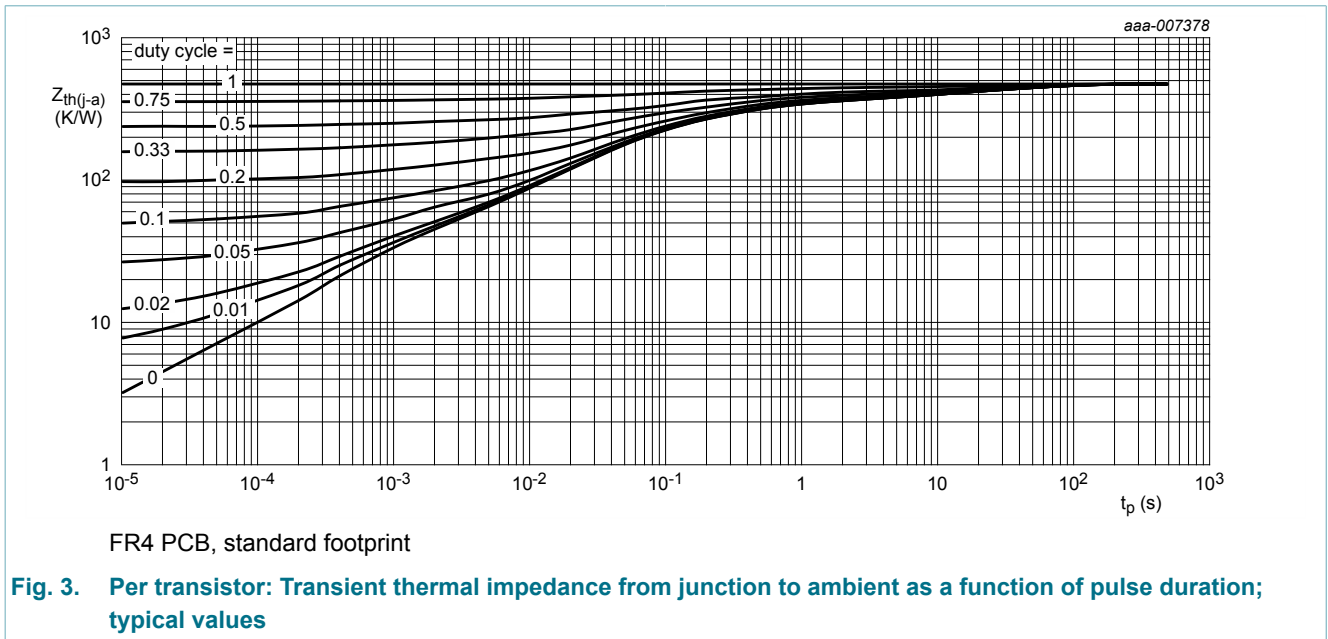
Fig. 2. Per device: Power derating curve

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per transistor							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	543	K/W
Per device							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	357	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per transistor							
I_{CBO}	collector-base cut-off current (emitter open)	$V_{CB} = -50\text{ V}; I_E = 0\text{ A}; T_{amb} = 25\text{ °C}$		-	-	-100	nA
I_{CEO}	collector-emitter cut-off current (base open)	$V_{CE} = -30\text{ V}; I_B = 0\text{ A}; T_{amb} = 25\text{ °C}$		-	-	-1	μA
		$V_{CE} = -30\text{ V}; I_B = 0\text{ A}; T_{amb} = 150\text{ °C}$		-	-	-5	μA
I_{EBO}	emitter-base cut-off current (collector open)	$V_{EB} = -5\text{ V}; I_C = 0\text{ A}; T_{amb} = 25\text{ °C}$		-	-	-400	μA
h_{FE}	DC current gain	$V_{CE} = -5\text{ V}; I_C = -5\text{ mA}; T_{amb} = 25\text{ °C}$		30	-	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -0.5\text{ mA}; T_{amb} = 25\text{ °C}$		-	-	-150	mV
$V_{I(off)}$	off-state input voltage	$V_{CE} = -5\text{ V}; I_C = -100\text{ μA}; T_{amb} = 25\text{ °C}$		-	-1.1	-0.8	V
$V_{I(on)}$	on-state input voltage	$V_{CE} = -0.3\text{ V}; I_C = -10\text{ mA}; T_{amb} = 25\text{ °C}$		-2.5	-1.8	-	V
R1	bias resistor 1	$T_{amb} = 25\text{ °C}$	[1]	7	10	13	kΩ
R2/R1	bias resistor ratio		[1]	0.8	1	1.2	
C_C	collector capacitance	$V_{CB} = -10\text{ V}; I_E = 0\text{ A}; f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$		-	-	3	pF
f_T	transition frequency	$V_{CE} = -5\text{ V}; I_C = -10\text{ mA}; f = 100\text{ MHz}; T_{amb} = 25\text{ °C}$	[2]	-	180	-	MHz

[1] See section "Test information" for resistor calculation and test conditions.

[2] Characteristics of built-in transistor

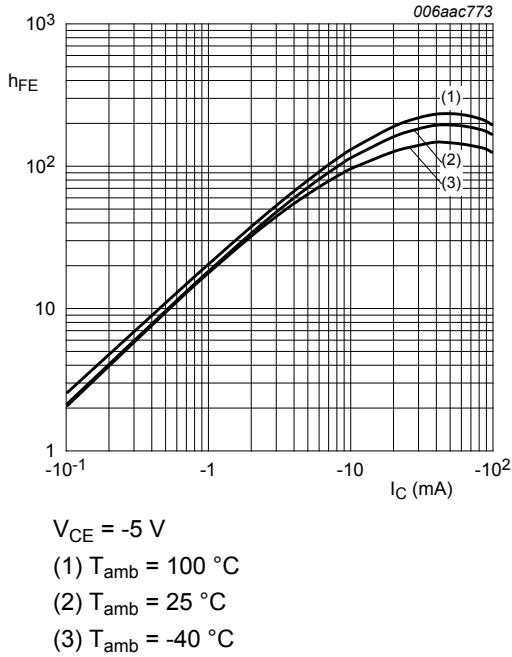


Fig. 4. DC current gain as a function of collector current; typical values

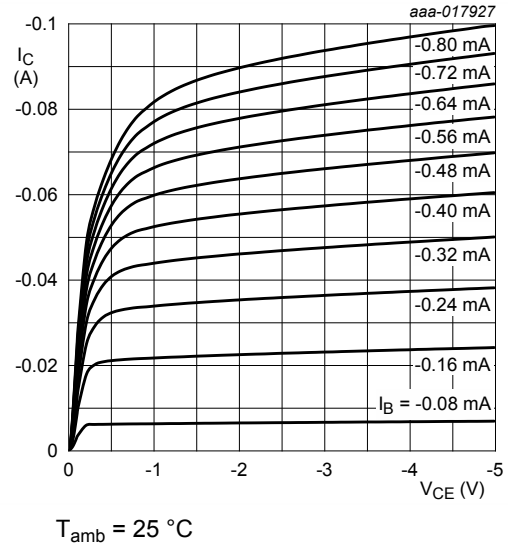


Fig. 5. Collector current as a function of collector-emitter voltage; typical values

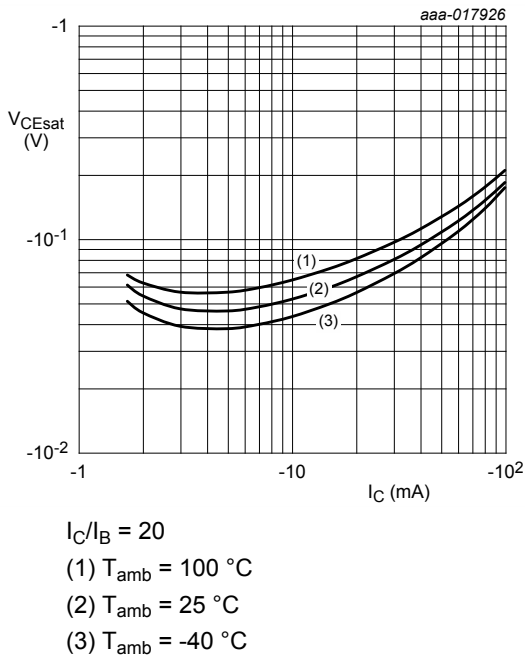


Fig. 6. Collector-emitter saturation voltage as a function of collector current; typical values

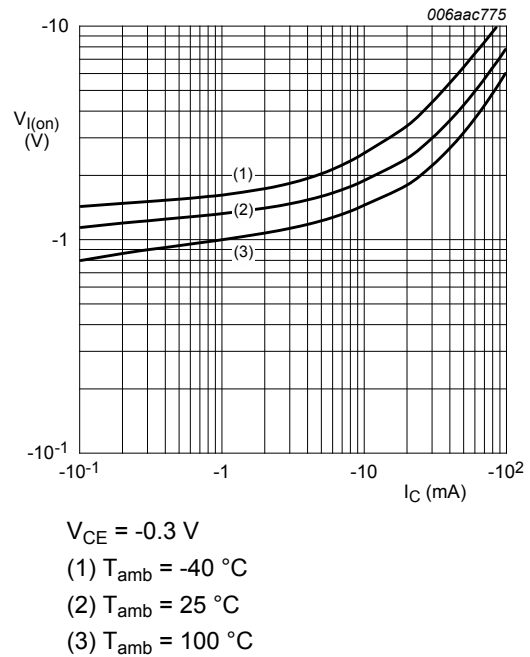
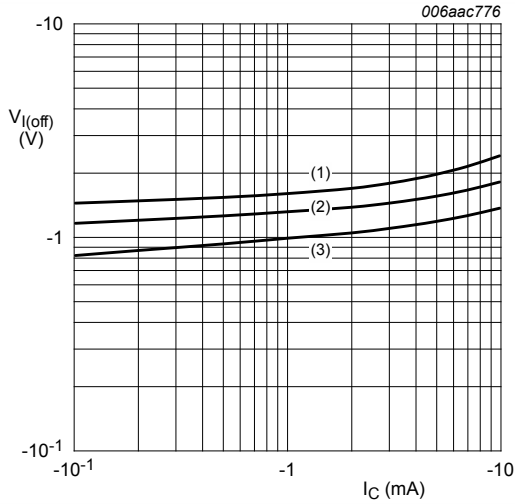
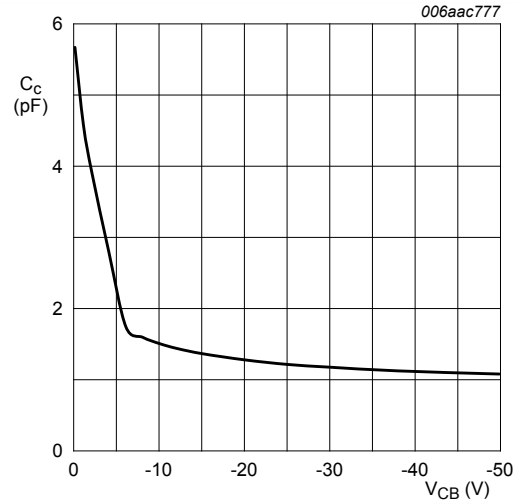


Fig. 7. On-state input voltage as a function of collector current; typical values



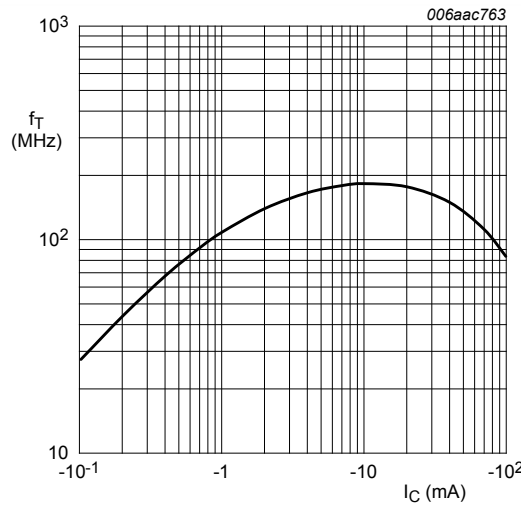
$V_{CE} = -5$ V
 (1) $T_{amb} = -40$ °C
 (2) $T_{amb} = 25$ °C
 (3) $T_{amb} = 100$ °C

Fig. 8. Off-state input voltage as a function of collector current; typical values



$f = 1$ MHz; $T_{amb} = 25$ °C

Fig. 9. Collector capacitance as a function of collector-base voltage; typical values



$V_{CE} = -5$ V; $T_{amb} = 25$ °C

Fig. 10. Transition frequency as a function of collector current; typical values of built-in transistor

11. Test information

11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

11.2 Resistor calculation

- Calculation of bias resistor 1 (R1)

$$R1 = \frac{V(I12) - V(I11)}{I12 - I11}$$

- Calculation of bias resistor ratio (R2/R1)

$$\frac{R2}{R1} = \frac{V(I14) - V(I13)}{R1 \cdot (I14 - I13)} - 1$$

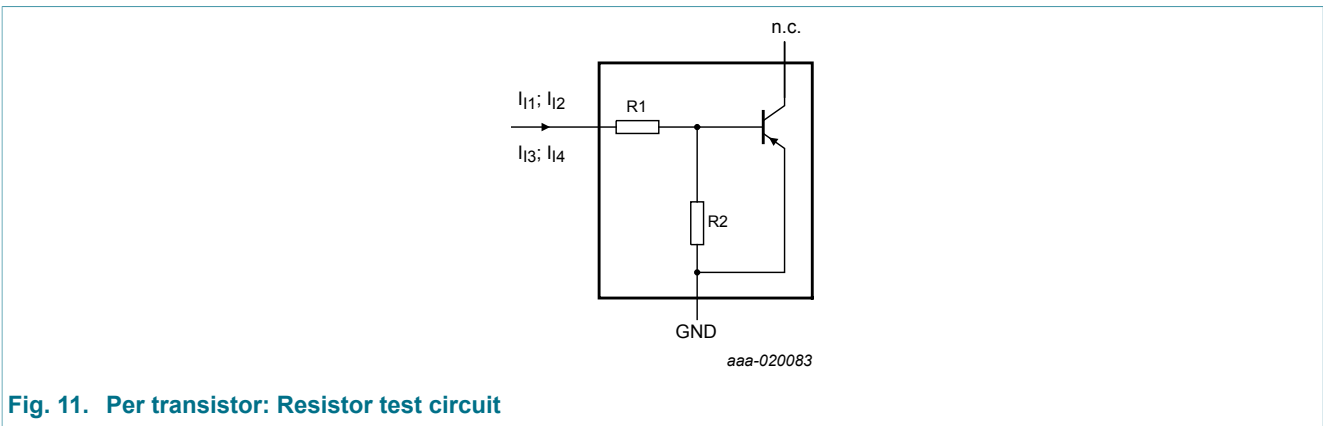


Fig. 11. Per transistor: Resistor test circuit

11.3 Resistor test conditions

Table 8. Resistor test conditions

R1 (kΩ)	R2 (kΩ)	Test conditions			
		I11	I12	I13	I14
10	10	-350 μA	-450 μA	350 μA	450 μA

12. Package outline

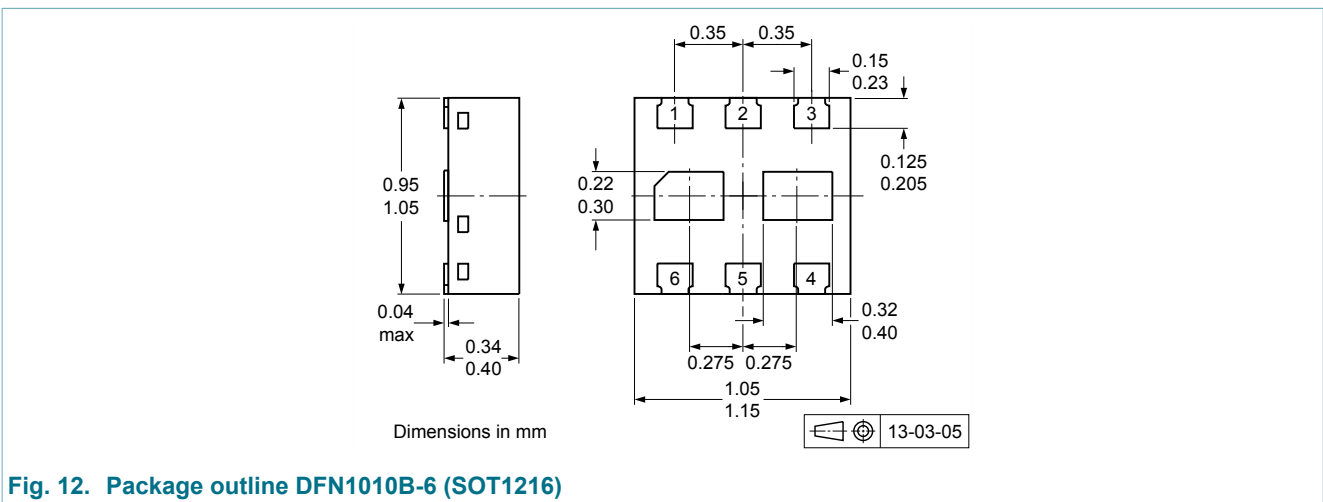


Fig. 12. Package outline DFN1010B-6 (SOT1216)

13. Soldering

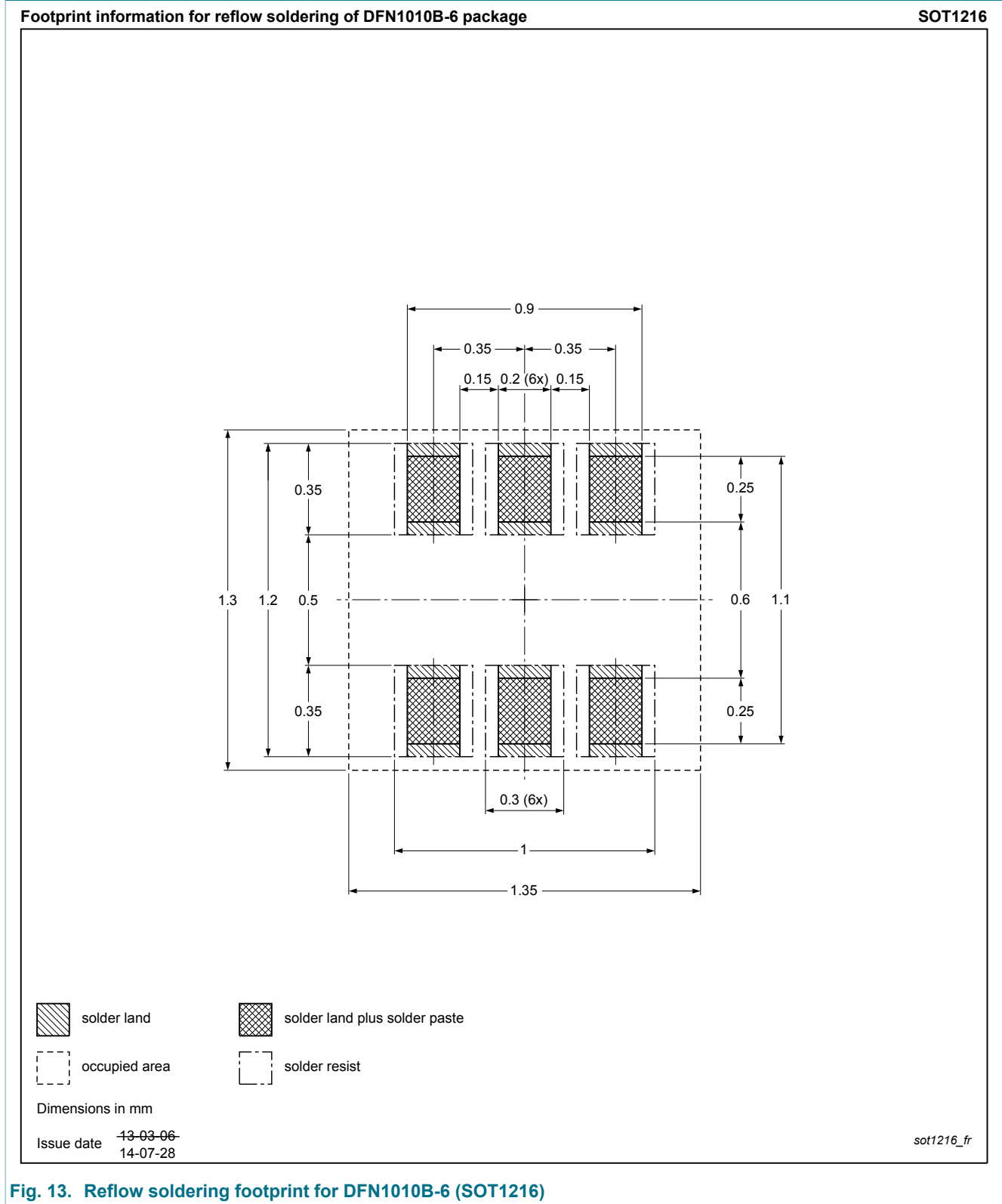


Fig. 13. Reflow soldering footprint for DFN1010B-6 (SOT1216)

14. Revision history

Table 9. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PQMB11 v.1	20151026	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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